Holding the Third Round of the "Bond Market Group" Meetings

The Financial Markets Department of the Bank of Japan will hold the third round of the "Bond Market Group" meetings in the following manner.

1. Date	Commercial banks group	June 6	at 4:00 p.m.
	Securities firms group	June 6	at 5:30 p.m.
	Buy-side group	June 7	at 5:00 p.m.

2. Place The Head Office of the Bank of Japan

3. Participants

- Persons in charge of bond market issues in financial institutions, participating in the "Bond Market Survey"
- Director-General of the Financial Markets Department, Head of Coordination and Market Analysis Division, Head of Market Operations Division, Head of Market Infrastructure Division

4. Topic

The Bank will explain (1) the results of the "Bond Market Survey," (2) liquidity in the JGB Market, and (3) recent developments in the financial markets and market operations. The Bank will also exchange views with participants on these topics.

For further information, please contact the Bank of Japan at the following e-mail address. Market Infrastructure Division at the Financial Markets Department: post.fmd29@boj.or.jp